

Title (en)

TIN/COPPER ALLOYS CONTAINING PALLADIUM, METHOD FOR THEIR PREPARATION AND USE THEREOF

Title (de)

PALLADIUMHALTIGE ZINN-/KUPFERLEGIERUNGEN, VERFAHREN ZU DEREN HERSTELLUNG UND VERWENDUNG DAVON

Title (fr)

ALLIAGES D'ÉTAIN ET DE CUIVRE CONTENANT DU PALLADIUM, PROCÉDÉ POUR LEUR PRÉPARATION, ET UTILISATION ASSOCIÉE

Publication

EP 3332044 B1 20200101 (EN)

Application

EP 16767356 A 20160804

Priority

- IT UB20152876 A 20150805
- IB 2016054703 W 20160804

Abstract (en)

[origin: WO2017021916A2] Bronze alloys containing palladium are described, in which the palladium content is from 0.25 to 10% by weight calculated on the total weight of the alloy and the galvanic baths used for their production.

IPC 8 full level

C22C 9/02 (2006.01); **C25D 3/58** (2006.01); **C25D 7/00** (2006.01)

CPC (source: EP)

C22C 9/02 (2013.01); **C25D 3/58** (2013.01); **C25D 7/005** (2013.01)

Citation (opposition)

Opponent : Coventya Holding SAS

- WO 2017021916 A2 20170209 - BLUCLAD S R L [IT]
- US 2014055026 A1 20140227 - HUTIN OLIVIER [DE], et al
- US 5972526 A 19991026 - MATSUMOTO YOSUKE [JP], et al
- JP H06293990 A 19941021 - NIPPON SHINKINZOKU KAKO KK
- WO 2015039152 A1 20150326 - W GARHÖFER GES M B H ING [AT]
- EP 2799595 A1 20141105 - DELPHI TECH INC [US]
- RICHARD E DEPOTO AND AL GRUENWALD C., UYEMURA & CO. LTD., & JOERG WEBER AND KLAUS LEYENDECKER, UMICORE GALVANOTECHNIK GMBH: "White Bronze, Copper-Tin-Zinc Tri-metal: Expand- ing Applications and New Developments in a Changing Landscape", ELECTROPLATING, 20 May 2013 (2013-05-20), pages 1 - 16, XP055739739, Retrieved from the Internet <URL:www.pfonline.com/articles/white-bronze-copper-tin-zinc-tri-metal-ex-panding-applications-and-new-developments-in-a-changing-landscape>

Designated contracting state (EPC)

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